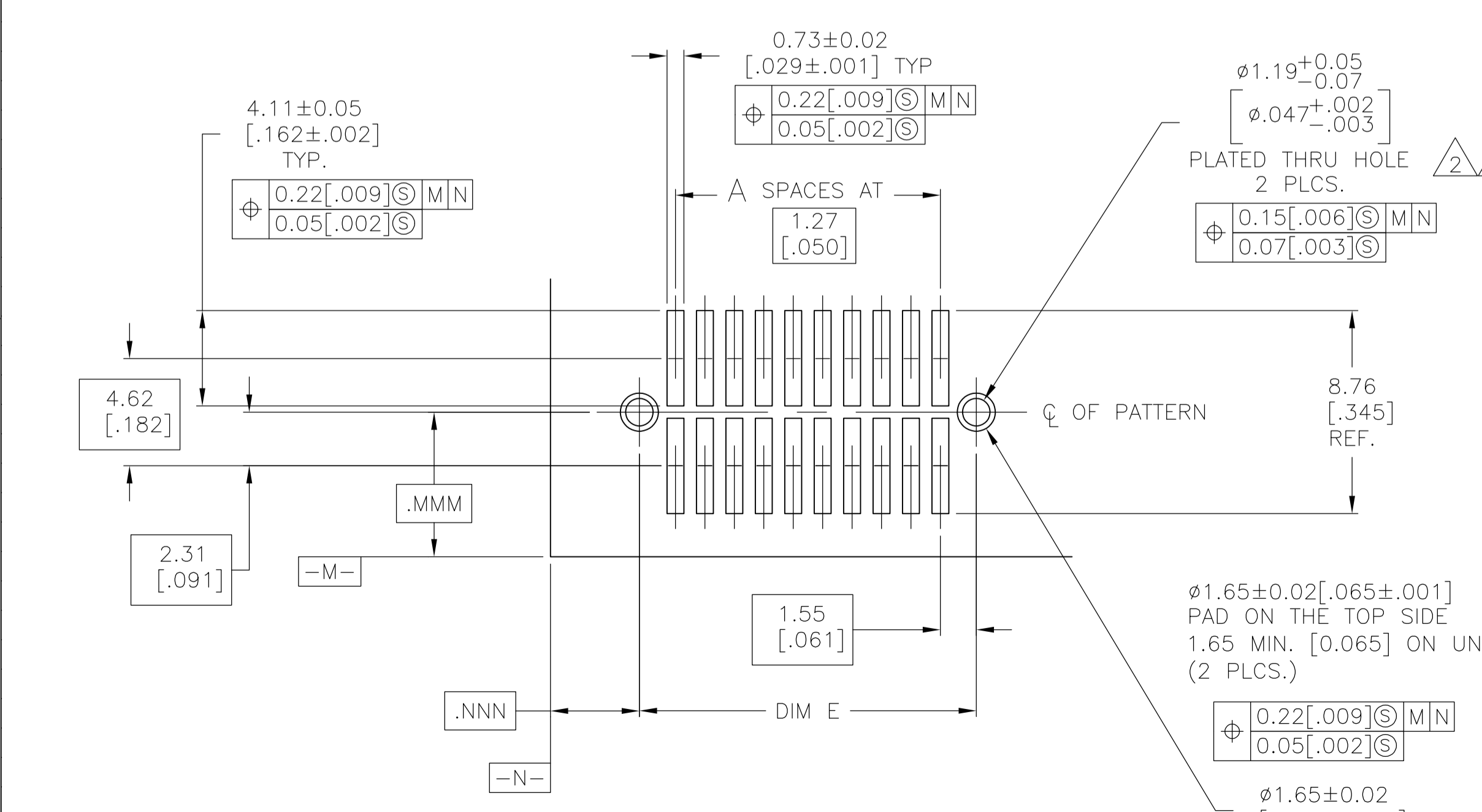
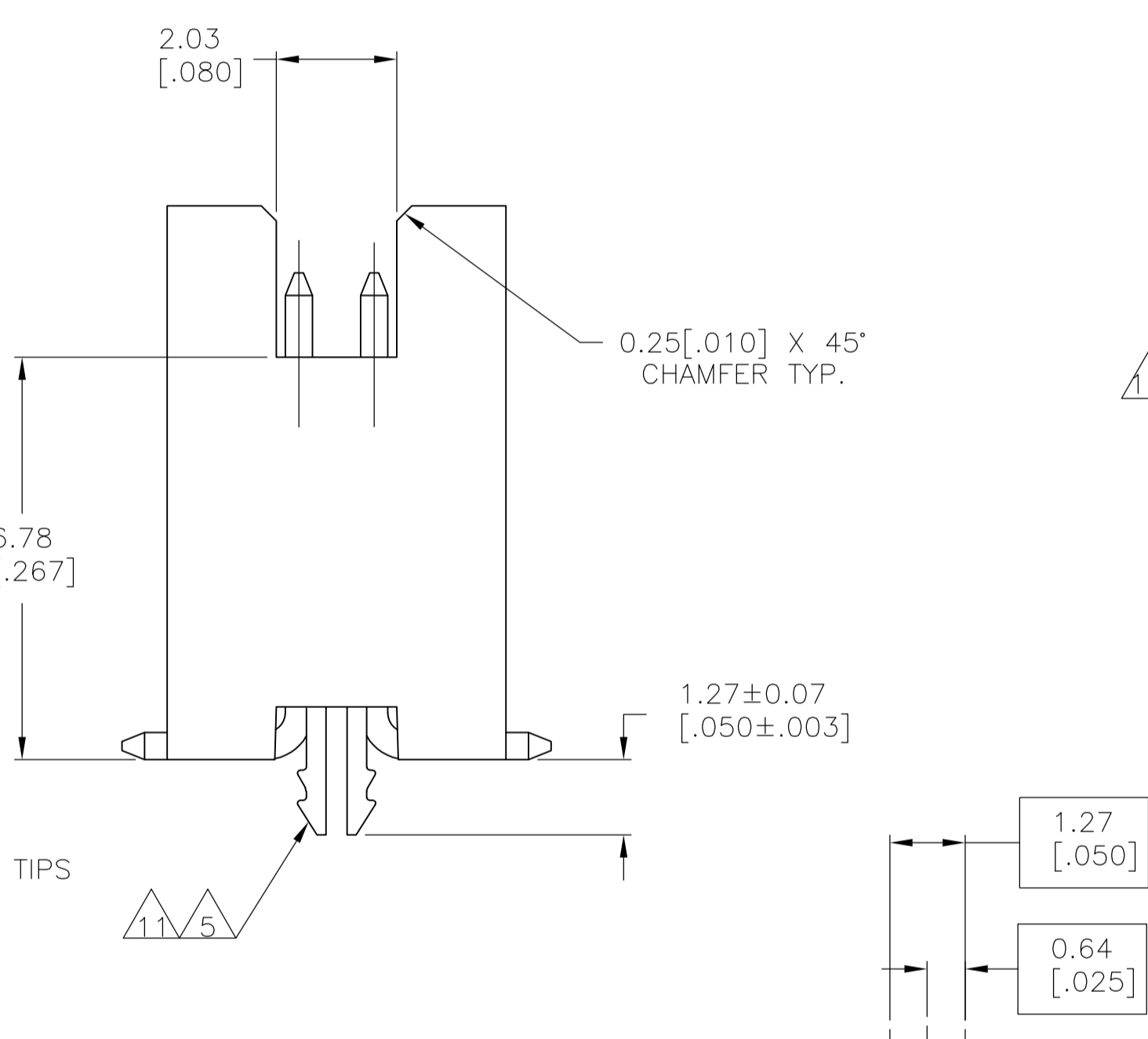
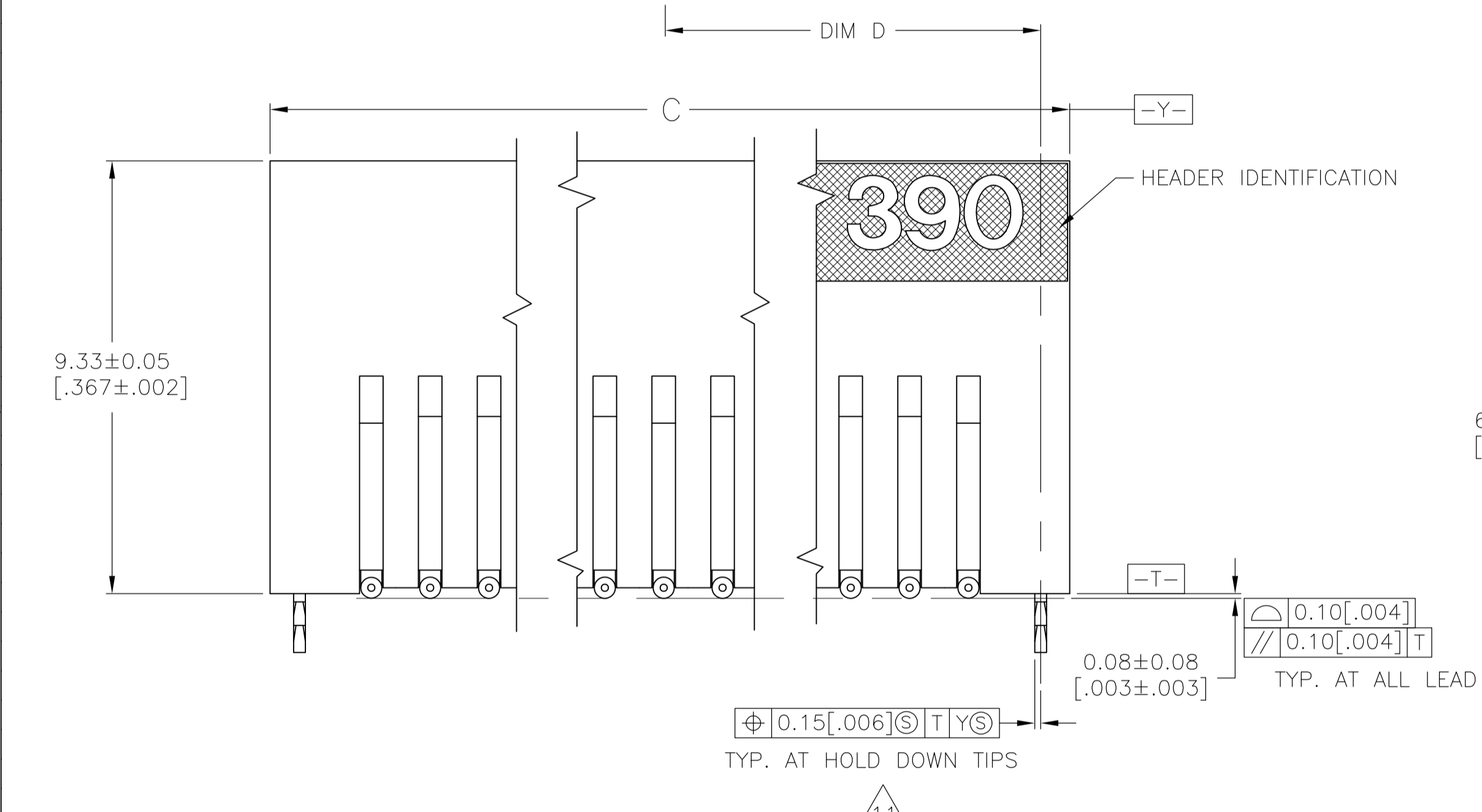
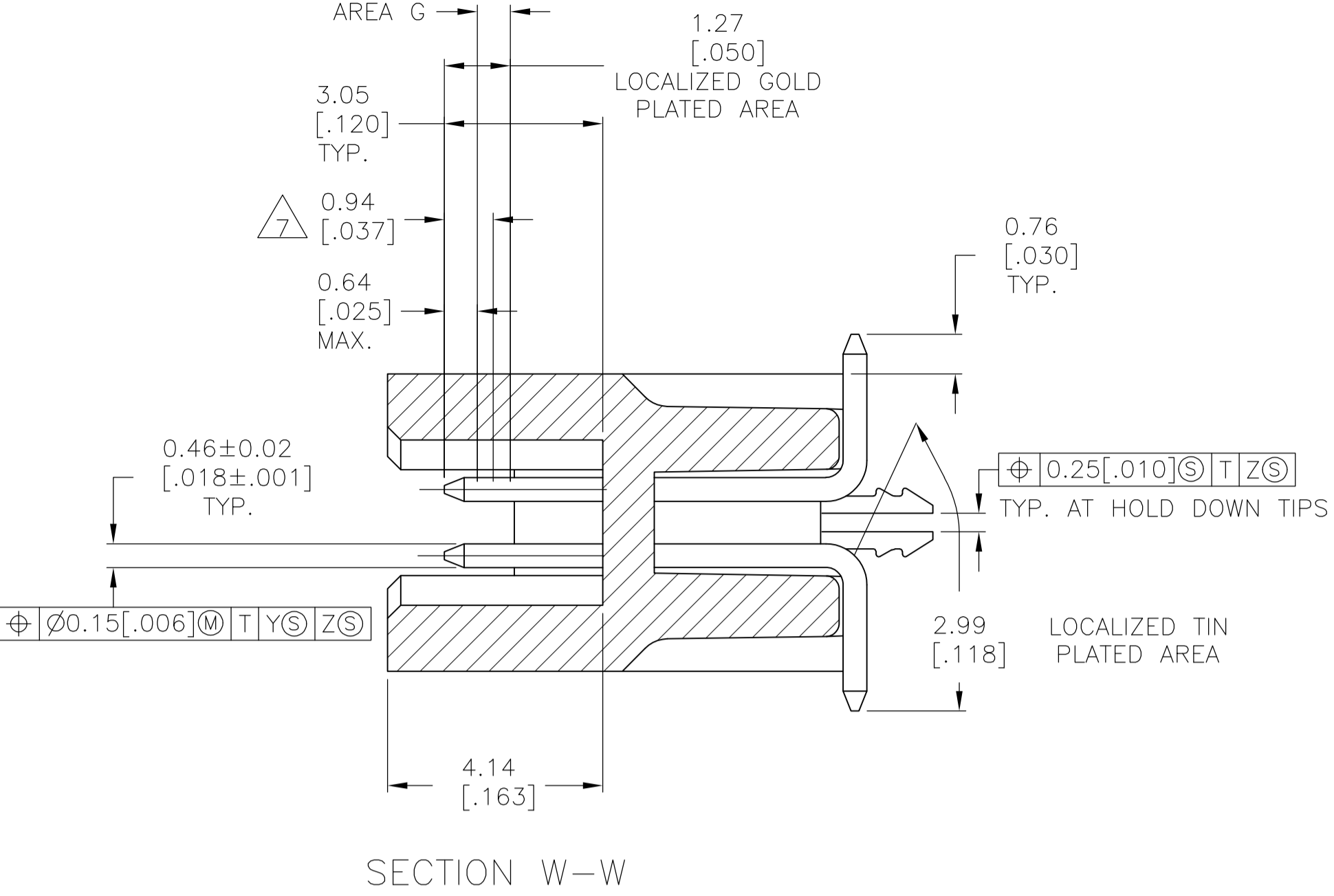
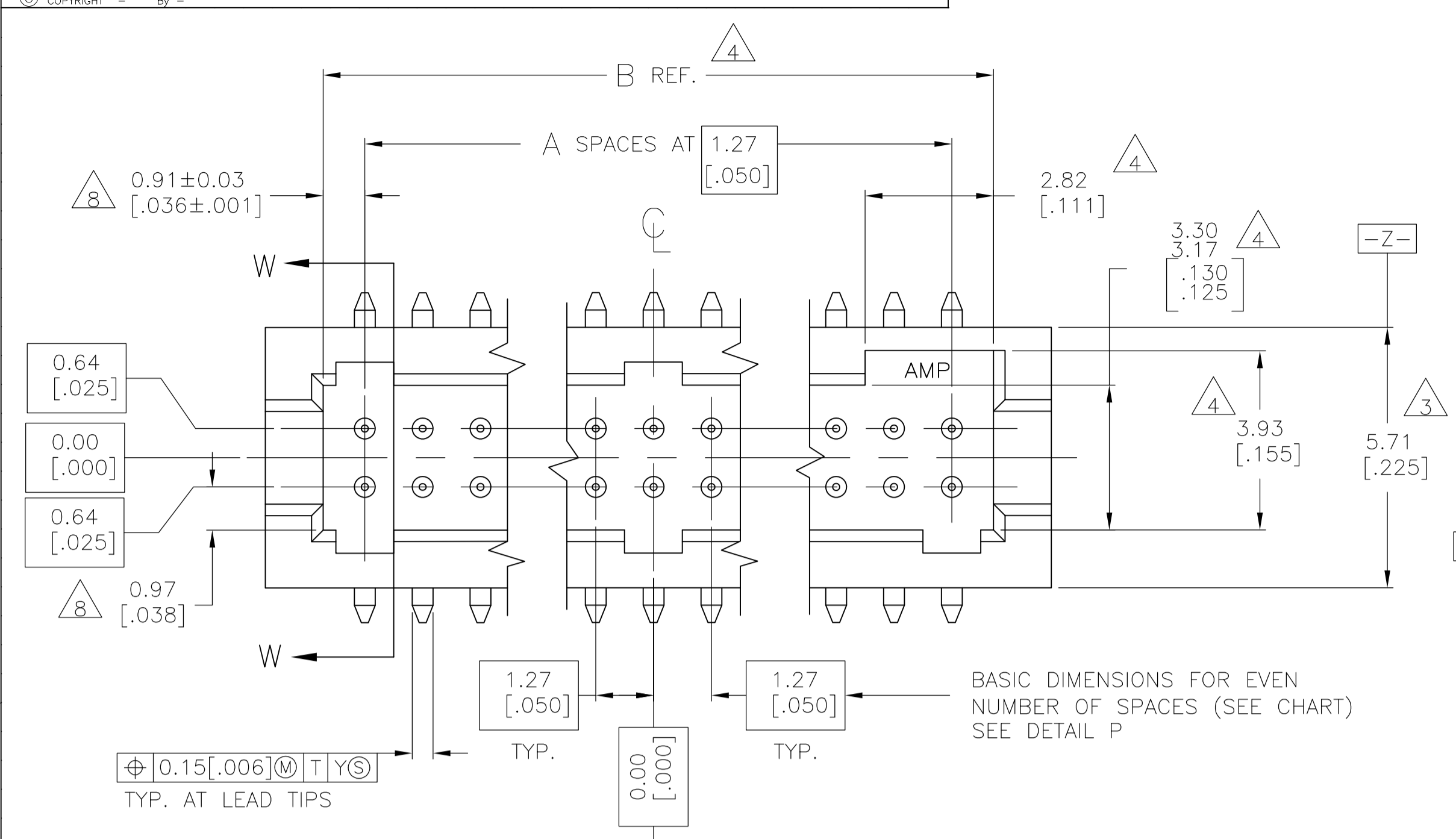


REVISONS		DATE	BY	APPV
L3	REVISED PER ECO-11-004587	11MAR11	RK	HMR



- 1 0.00076(.000030) GOLD AT POINT OF MEASUREMENT, 0.00051(.000020) MIN AT THE END POINTS OF AREA G, (LOCALIZED GOLD PLATE AREA), 0.0038(.000150) TIN-LEAD ON LOCALIZED TIN PLATED AREA, ALL OVER 0.0013(.000050) NICKEL.
- 2 USE 1.32±0.02(.0520±.0010) DRILLED HOLE (#55 DRILL). FINISH TO BE TIN-LEAD OVER 0.02 [.001] MIN COPPER.
- 3 DIMENSION APPLIES AT BASE OF SHROUD.
- 4 THE NOTED DIMENSIONS APPLY AT THE MATING FACE OF THE HOUSING.
- 5 0.0038 [.000150] TIN-LEAD ON HOLD DOWN, ALL OVER 0.0013 [.000050] NICKEL.
- 6 IF PLANNING TO USE MORE THAN ONE MATING PAIR OF CONNECTORS TO INTERCONNECT 2 BOARDS, PLEASE REFER TO SPACING PARAGRAPH IN APPLICATION SPEC, #114-7010
- 7 POINT OF MEASUREMENT
- 8 DIMENSIONS NOTED APPLY FROM THE BASIC DIMENSION LINE (NOT THE CIRCUIT CAVITY CENTER LINE) TO THE SURFACE INDICATED.
- 9 0.00076 (.000030) GOLD AT POINT OF MEASUREMENT, 0.00051(.000020) MIN AT THE END POINTS OF AREA G (LOCALIZED GOLD PLATE AREA), 0.0038(.000150) TIN ON LOCALIZED TIN PLATED AREA, ALL OVER 0.0013(.000050) NICKEL.
- 10 USE 1.32±0.02(.0520±.0010) DRILLED HOLE (#55 DRILL) FINISH TO BE TIN OVER 0.02(.001) MIN COPPER.
- 11 0.0038 (.000150) TIN ON HOLDDOWN, ALL OVER 0.0013 (.000050) NICKEL
- 12 ROHS 2002/95/EC COMPLIANT.
- 13 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

FINISH	E	D	C	B	A	NUMBER OF POSITIONS	PART NUMBER	
								9
						49	100	6-104693-0
						44	90	5-104693-9
						39	80	5-104693-8
						34	70	5-104693-7
						29	60	5-104693-6
						24	50	5-104693-5
						19	40	5-104693-4
						14	30	5-104693-3
						9	20	5-104693-2
						4	10	5-104693-1
						49	100	1-104693-0
						44	90	104693-9
						39	80	104693-8
						34	70	104693-7
						29	60	104693-6
						24	50	104693-5
						19	40	104693-4
						14	30	104693-3
						9	20	104693-2
						4	10	104693-1

RECOMMENDED BOARD LAYOUT SCALE 5:1

THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 01AUG08. KATE HELM. 8/12/91. CHK: D. GORENC. 8/12/91. APPV: D. GORENC. 8/12/91. NAME: D. GORENC. PRODUCT SPEC: 108-1332. APPLICATION SPEC: 114-7010. MATERIAL: INDUCTIVE LEAD ASSEMBLY. FINISH: SEE TABLE. WEIGHT: -. SIZE: A1. CUSTOMER DRAWING. SCALE: 10:1. SHEET: 1 OF 1. REV: L3.

STE TE Connectivity

HEADER ASSEMBLY, SURFACE MOUNT, AMPMODU 50/50 GRID (9.90 [.390] MATED HEIGHT)

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[5-104693-3](#)